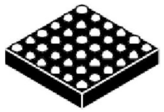
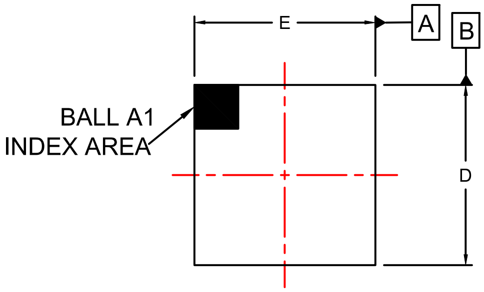
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



WLCSP36 2.06x2.06x0.432
CASE 567XU
ISSUE O

DATE 26 APR 2019

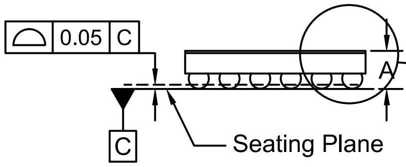


TOP VIEW

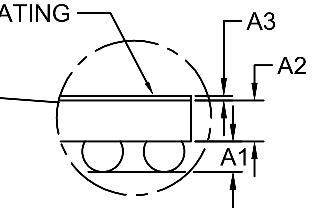
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

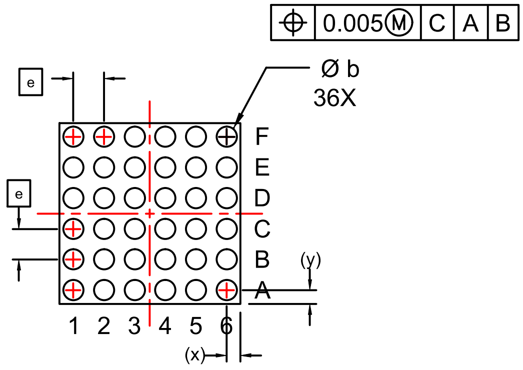
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.391	0.432	0.473
A1	0.154	0.174	0.194
A2	0.215	0.233	0.251
A3	0.022	0.025	0.028
b	0.211	0.231	0.251
D	2.03	2.06	2.09
E	2.03	2.06	2.09
e	0.35 BSC		
x	0.140	0.155	0.170
y	0.140	0.155	0.170



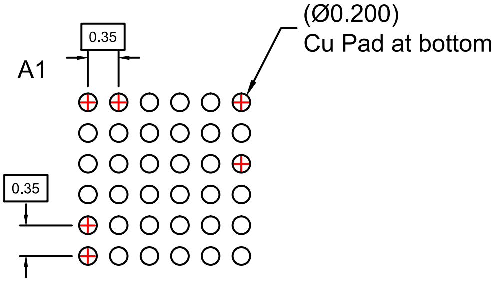
SIDE VIEW



DETAIL A



BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT*
(NSMD PAD TYPE)

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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DESCRIPTION:	**WLCSP36 2.06x2.06x0.432**	**PAGE 1 OF 1**